Lenovo P1 Gen 8

Version: 2.0 | 03/16/2026

Product Name	P1 Gen 8
Product Display Name	ThinkPad P1 Gen 8
Information Date	5-Sep-25

SECTION I: SYSTEM OVERVIEW

Description	Designed with the mobile-first user in mind, the Lenovo ThinkPad P1 is the perfect combination of workstation know-how, ultra-premium performance, Artificial Intelligence ready, and true mobility. All new premier sustainable design, the ultimate in beauty and power.

CPU

Processor Support	Intel Core Ultra Series 2 – H-Series (35W) Core 5, 7, and 9
Type	BGA
Preloaded	Windows 11 Pro 64-bit (24H2) Windows 11 Home 64-bit Windows 11 Home Single Language 64-bit Windows 11 Home Chinese Language Edition 64-bit Ubuntu Linux 64-bit (Version 24.04) Fedora 41 Linux (depending on NVIDIA open source driver status) No Operating System
Supported	Ubuntu Linux 24.04 Cert only Red Hat Enterprise Linux (RHEL) 9.6 (depending on NVIDIA open source driver status) Debian 13 qualification (not for limited configurations only)

Memory

Number of DIMM Slots	n/a
Channels	Dual Channel
Type	LPDDR5 LPCAMM2
ECC Support	No
Speed	Up to 7467MT/s
Max DIMM LPCAMM2 Size	64GB
Max System Memory	64GB
Min System Memory	16GB
Soldered Memory	None
Disclaimers	No ECC memory on P1 Gen 8

Storage

Storage Slots	2x M.2 2280
SATA	No
PCIe	Solid State Drive, 2x OPAL2 PCIe NVMe M.2 – TLC
SAS	None
Interface	PCIe Gen 5 Performance or Gen 4 Value
Security	OPAL2 for NVMe SSD
Optional Hard Disk Drive Controllers	None
Disclaimers	Dual slot storage is available with all CPU & GPU options

Video

Integrated Graphics	Processor Graphics Intel® Arc Pro Graphics Utilized via “Hybrid Mode” in BIOS
Discrete Graphics	NV RTX PRO 1000 Blackwell, 2000 Blackwell
Adapter	None
Bus Interface	PCI Express 5.0

Display

Resolutions	WUXGA (FHD+) / WQUXGA (UHD+) / 3.2k T-OLED Touch

Camera

Resolution	5MP RGB + IR Hybrid Camera
Frames per Second	30 fps
Focus	Fixed 50cm
Camera Interface	USB 2.0
IR Camera	Yes

Keyboard

Number of Keys	US : 84 / UK : 85 / JP :89
Numpad	No
Size	100% ISO
Function Key Features	Yes
Backlit	Yes
Keyboard size	2024 Full size KB without NumPad (Bottom loading)
Key stroke	1.5mm
Key pitch	19.05 mm (Vertical & Horizontal)
Keyboard backlight	Yes
Keyboard thickness	4.0mm

TrackPad / Fingerprint Reader

TrackPoint Details	CS22 4.8 mm TrackPoint w/ TTS
Finger Print Reader Model	Synaptics Metallica 8×8 FPR, MoC – integrated with Power button
Multi-Touch	Yes
Resolution	1000 ppi
TrackPad/Haptic TouchPad thickness	3.65mm
TrackPad/Haptic TouchPad type	Haptic TouchPad
TrackPad size	135mm x 85mm
TrackPad material/finish	Glass surface

I/O – Ports and Connectors

USB	1x USB-A (10Gbps)
Thunderbolt	1x USB-C (Thunderbolt™ 4) 2x USB-C (Thunderbolt™ 5)

HDMI	1x HDMI 2.1
Audio Combo Jack	1x Microphone & Headphone Combo Jack (3.5mm)
Media Card Reader	Dedicated SD Express 7.0 Card Reader (Backwards compatible with UHS-I & UHS-II) (MMC,SD,SDHC SDXC)
Smart Card Reader	None
Power Connector	DC-In via USB-C® (Thunderbolt™ 5) PD 3.1
Docking Port	Docking Via USB-C® (Thunderbolt™ 5) PD 3.1
VirtualLink	None
Network adapter	No native RJ-45 port RJ-45 functionality provided via USB-C® to Ethernet Adapter
Disclaimers	HDMI 2.1: Up to 8K/60Hz

Power Connector

Main	DC-In via USB-C® (Thunderbolt™ 5) PD 3.1
USB-C	see above
Disclaimers	normal charge via 100W and fast charge via 140W charger

Ethernet

Vendor	N/A
Count	N/A
EEPROM	N/A
Speeds	N/A
Functions	N/A
Connectors	No native RJ-45 port
Disclaimers	RJ-45 functionality provided via USB-C® to Ethernet Adapter

WWAN

Model	N/A
Disclaimers	N/A

Near Field Communications

Model	Foxconn NXP NPC300 NFC

Disclaimers	NFC supported for EMEA only

Audio

Vendor	Realtek
Type	Intel High Definition Audio (2 channel)
Internal Speaker	2 channel
Connectors	Microphone & Headphone Combo Jack (3.5mm)
Chipset	ALC3306 w/ Smart Amp
Number of Channels	4-channel DAC, 4-channel ADC
Number of Bits/Audio Resolution	16/20/24-bit PCM format
Sampling Rate (Recording/Playback)	44.1k/48k/96k/192kHz sample rate
Signal to Noise Ratio	Mic In: 95dB FSA Headphone Out@32ohm: 100dB FSA
Analog Audio	None
Dolby Digital	Dolby ATMOS
Digital Out (S/PDIF)	No
Speaker Power Rating	2W@4ohm/ch

Power adapter

Type	140W Type-C PD 3.1 EPR AC Adapter
Dimensions	(120 x 62.5 x 22mm)
Weight	Max 340g
Input Voltage	100-240V

Security

TPM	Version 2.0
Asset ID	Yes
vPro	Intel vPro for WS

Chassis Information

Format	16" Clamshell
Color & Material	Black Aluminum

Thermal Solutions	Internal Dual Fan, Flex Cooling, Intelligent Cooling, Dual by-pass design, Liquid Metal Cooling
Dimensions	Length 13.95 inches 354.30 millimeters Width 9.49 inches 241.00 millimeters Height 0.39 (front) / 0.62 (rear), 0.81 (max) inches 9.9 (front) / 15.8 (rear), 20.6 (max) millimeters
Weight	Starting weight: 1.84kgs/4.06lbs (T-OLED + UMA model)

Packaging Parameters

Height (mm)	329mm
Height (inch)	12.95in
Width (mm)	518mm
Width (inch)	20.39in
Depth (mm)	80mm
Depth (inch)	3.14in
Weight (kgs)	3.2kgs
Weight (lbs)	7.05lbs

Security & Serviceability

Hardware Maintenance Manual	P1 Gen 8 HMM
Drivers & Software	P1 Gen 8 Drivers & Software
Self Healing BIOS	Yes
Access Panel	Removable bottom cover
Number of Screws	6
Swappable Components	Bottom cover, battery, 1x right side USB-C, M.2 Solid State Drive, LPCAMM2 memory module, speaker, RTC battery
Storage Slots	2 slots
Memory Slots	0 (no slots for CAMM2)
System Board	n/a
Restore CD/DVD/USB Set	None, Restore Media available via Lenovo Customer Support Center
Cable Lock Support	Security-lock slot, Optional Kensington Cable Lock
Power-On Password	Yes
Hard Disk Password	Yes; User and Master hard disk password
Supervisor Password	Yes

NIC LEDs (integrated)	None
Security Chip	Yes (for TPM 2.0)
Access Panel Key Lock	Bottom Cover Tamper Detection
Boot Sequence Control	Yes

Operating Environment

Operating – Air Temperature	At altitudes up to 2438 m (8000 ft) – Operating: 5°C to 35°C (41°F to 95°F)
Non Operating – Air Temperature	At altitudes up to 2438 m (8000 ft) – Storage: 5°C to 43°C (41°F to 109°F)
Humidity	Operating: 8% to 95% at wet-bulb temperature 23°C (73°F) Storage: 5% to 95% at wet-bulb temperature 27°C (81°F)
Corrosive Gas	G1
Particulates	P1

SECTION II: SUPPORTED COMPONENTS

Supported Components

Processor	Intel® Core™ Ultra 5 235H processor (E-cores up to 4.4 GHz P-cores up to 5.0 GHz) Intel® Core™ Ultra 7 255H processor (E-cores up to 4.4 GHz P-cores up to 5.1 GHz) Intel® Core™ Ultra 7 265H processor (E-cores up to 4.5 GHz P-cores up to 5.3 GHz) Intel® Core™ Ultra 9 285H processor (E-cores up to 4.5 GHz P-cores up to 5.4 GHz)
Memory Support	LPDDR5x 7467MT/s LPCAMM2
Chipset (PCH)	OnPkg PCH-P
Size of BIOS Flash	64MB + 16MB
Super I/O	None
Clock	Crystal
Audio	Dolby Atmos
Ethernet	No native RJ-45 port RJ-45 functionality provided via USB-C® to Ethernet Adapter

Memory

System Capacity Options	16GB 32GB 64GB
Memory Types	16GB LPDDR5x 7467MT/s LPCAMM2 32GB LPDDR5x 7467MT/s LPCAMM2 64GB LPDDR5x 7467MT/s LPCAMM2
Brand of Memory	Samsung Ramaxel Micron
Memory Speed	7467MT/s
Disclaimers	No ECC memory on P1 Gen 8

Storage

2.5" SAS Hard Disk Drive (HDD)	None
2.5" SATA Hard Disk Drive (HDD)	None
2.5" SATA Solid State Drive (SSD)	None
M.2 (NGFF) PCIe Solid State Drive (SSD)	256GB OPAL2 PCIe 4×4 Value TLC (M.2 2280-S3) 512GB OPAL2 PCIe 4×4 Value TLC (M.2 2280-S3) 1TB OPAL2 PCIe 4×4 Value TLC (M.2 2280-S3) 512GB OPAL2 PCIe 5×4 Performance TLC (M.2 2280-S3) 1TB OPAL2 PCIe 5×4 Performance TLC (M.2 2280-S3) 2TB OPAL2 PCIe 5×4 Performance TLC (M.2 2280-S3) 4TB OPAL2 PCIe 5×4 Performance TLC (M.2 2280-S3)
2.5" PCIe Solid State Drive (SSD)	None
Brand of Drive	SanDisk Micron Samsung UnionMem Hynix Kioxia
Intel Optane Storage Technology	None
RAID	Optional, Selectable in BIOS
RAID Level and Requirements	RAID-0/1

Removeable Media

Media Card Reader Specifications	SD Express 7.0
Disclaimers	Backwards compatible with UHS-I and UHS-II

SECTION III: Supported Component Detail

CPU Specifications

CPU	Intel® Core™ Ultra 5 235H processor (E-cores up to 4.4 GHz P-cores up to 5.0 GHz)	Intel® Core™ Ultra 7 255H processor (E-cores up to 4.4 GHz P-cores up to 5.1 GHz)	Intel® Core™ Ultra 7 265H processor (E-cores up to 4.5 GHz P-cores up to 5.3 GHz)	Intel® Core™ Ultra 9 285H processor (E-cores up to 4.5 GHz P-cores up to 5.4 GHz)
Integrated Graphics	Intel® Arc Pro Graphics	Intel® Arc Pro Graphics	Intel® Arc Pro Graphics	Intel® Arc Pro Graphics
# of Cores	4 P-cores and 8 E-cores	6 P-cores and 8 E-cores	6 P-cores and 8 E-cores	6 P-cores and 8 E-cores
# of Threads	14	16	16	16
Processor Base Frequency	E-cores up to 1.8 GHz / P-cores up to 2.4 GHz	E-cores up to 1.5 GHz / P-cores up to 2.0 GHz	E-cores up to 1.7 GHz / P-cores up to 2.2 GHz	E-cores up to 2.7 GHz / P-cores up to 2.9 GHz
Max Turbo Frequency	E-cores up to 4.4 GHz / P-cores up to 5.0 GHz	E-cores up to 4.4 GHz / P-cores up to 5.1 GHz	E-cores up to 4.5 GHz / P-cores up to 5.3 GHz	E-cores up to 4.5 GHz / P-cores up to 5.4 GHz
Cache	18 MB	24 MB	24 MB	24 MB
TDP	35 W	35 W	35 W	35 W

Display Specifications

Model	WUXGA IPS Non-Touch, Low Power	WQUXGA IPS Non-Touch	3.2k Tandem-OLED Touch
Resolution	FHD+ (1920 x 1200)	UHD+ (3840 x 2400)	3.2k (3200 x 2000)
Diagonal	16"	16"	16"
Aspect Ratio	16:10	16:10	16:10
Backlight	LED	LED	N/A
PPI	142	283	236
Active Area	FHD+: 344.68mm x 215.42mm	UHD+: 344.678mm x 215.424mm	3.2k: 344.448mm x 215.280mm
Refresh Rate	Max 60Hz	Max 60Hz	40-120Hz VRR
Contrast Ratio	FHD+: 1200:1	UHD+: 1500:1	3.2k: 100,000:1
Viewing Angle	FHD+: 89/89/89/89 degree	UHD+: 85/85/85/85 degree	3.2k: 85/85/85/85 degree
Color gamut	100% sRGB	100% DCI-P3	100% DCI-P3
Brightness	500 nits	800 nits	SDR 600 nits / HDR 1500 nits
HDR	N/A	HDR400 Dolby Vision	HDR600 Dolby Vision
Color Depth	FHD+: 16.7M (8-bit)	UHD+: 1064M (8-bit + 2 FRC)	3.2k: 1074M (8-bit + 2 FRC)

Interface	FHD+: eDP 1.4b	UHD+: eDP 1.4b	3.2k: eDP 1.4b
Panel ID Recognition	EDID in BIOS Table	EDID in BIOS Table	EDID in BIOS Table
Weight	320g max	330g max	199g max
Color Calibrator	X-Rite Factory Color Calibration	X-Rite Factory Color Calibration	X-Rite Factory Color Calibration
Panel Technology	IPS, Anti-Glare	IPS, Anti-Glare	Tandem-OLED, AGARAS
Touch Panel	None	None	Multi-Finger Touch Panel

SSD Specifications

2.5" SATA Solid State Drive (SSD)	N/A
M.2 (NGFF) PCIe Solid State Drive (SSD)	2x M.2 2280-S3 PCIe
2.5" PCIe Solid State Drive (SSD)	N/A
Intel Optane Storage Technology	N/A

Solid State Storage Devices

Supported Types	M.2	M.2
Dimensions inches/centimeters (W x D x H)	22.0 (+-0.15) x 80.0 (+-0.15) x 2.3 (max)	22.0 (+-0.15) x 80.0 (+-0.15) x 2.3 (max)
Size	M.2 2280-S3	M.2 2280-S3
Interface Type	PCIe NVMe	PCIe NVMe
Read/Write IOPS Specifications	Read: 600K (1TB), 450K (512GB), 250K (256GB) Write: 500K (1TB,512GB), 400K (256GB) IOPS, 4K Random, 8 threads, queue depth of 32, data set size of 1GB.	Read: 1500K (4TB/2TB), 1200K (1TB), 1000K (512GB) Write: 1500K (4TB/2TB/1TB), 1200K (512GB) IOPS, 4K Random, 8 threads, queue depth of 32, data set size of 1GB.
Bandwidth Performance	PCIe Gen4x4 Value – 256GB-1TB	PCIe Gen5x4 Performance – 512GB-4TB
Power Consumption (Max)	3.0A (duration for 10 us)	4.5A (duration for 10 us)
Active(AVG)	5W	10W
Idle	5mW (L1.2)	5mW (L1.2)
Min MTBF	2,000,000 (h)	2,000,000 (h)
Min Sequential Read	5000MB/s (1TB), 4800MB/s (512GB), 4000MB/s (256GB)	14000MB/s (4TB/2TB/1TB), 11000MB/s (512GB)
Min Sequential Write	4000MB/s (1TB/512GB), 2000MB/s (256GB)	12000MB/s (4TB/2TB), 11000MB/s (1TB), 5500MB/s (512GB)
Hardware Encryption	OPAL	OPAL

Discrete Graphics Adapter

Laptop GPUs	NVIDIA RTX PRO 1000 Blackwell Laptop GPU	NVIDIA RTX PRO 2000 Blackwell Laptop GPU
NVIDIA CUDA Processing Cores	2560	3328
NVIDIA RT Cores	(4th Gen)	(4th Gen)
Tensor Cores	(5th Gen)	(5th Gen)
GPU Memory	8GB	8GB
Peak Memory Bandwidth	384 GB/s	384 GB/s
Memory Type	GDDR7	GDDR7
Memory Interface	128-bit	128-bit
DisplayPort	2.1b	2.1b
Open GL	4.6	4.6
Shader Model	7	7
DirectX	12 Ultimate	12 Ultimate
PCIe Generation	5	5
Single Precision Floating-Point Performance	13.6	17.7
Tensor Performance	193	231.6
NVIDIA FXAA/TXAA Anti-Aliasing	Yes	Yes
NVIDIA RTX Desktop Manager	No	No
Vulkan Support	Yes	Yes
NVIDIA Optimus	Yes	Yes
NVIDIA Max-Q Technology	Yes	Yes
NVENC/NVDEC	Yes	Yes

WLAN

Model	Intel Wi-Fi 7 BE201 (Fillmore Peak 2) + BT5.4 (HW Ready)
Antenna Diversity	Supported
MIMO	Supported
Radio ON/OFF Control	Supported
Connector interface	M.2 PCIe
Operating Temperature (Adapter Shield)	0c to +80c
Humidity Non-Operating	50%~90% Rh non condensing (at temperatures of 25c to 35c)
Operating Systems	Microsoft Windows 11, Linux, Fedora
Wi-Fi Alliance	Wi-Fi CERTIFIED 7, Wi-Fi CERTIFIED 6 with Wi-Fi 6E, Wi-Fi CERTIFIED a/b/g/n/ac, WMM, WMM-

	PowerSave, WPA3, Protected Management Frames, Wi-Fi Direct, Wi-Fi Agile Multiband
IEEE WLAN Standard	IEEE 802.11-2020 and select amendments (selected feature coverage) IEEE 802.11a, b, d, e, g, h, i, k, n, r, u, v, w, ac, ax, be; Fine Timing Measurement based on 802.11-2016, Wi-Fi Location R2 (802.11az) HW readiness
Roaming	Support seamless roaming between access points
Bluetooth	Bluetooth 5.4
Authentication Protocols	802.1X EAP-TLS, EAP-TTLS/MSCHAPv2, PEAPv0 – MSCHAPv2 (EAP-SIM, EAP-AKA, EAP-AKA')
Encryption	128-bit AES-CCMP, 256-bit AES-GCMP
Regulatory	For a list of country approvals, please contact your local Intel representatives
US Government	FIPS 140-3
Product Safety	UL, C-UL, CB (62368-1)
Disclaimers	1) For more details, please refer to the Intel document as below. https://www.intel.com/content/www/us/en/products/sku/230078/intel-wifi-7-be200/specifications.html 2) Bluetooth version may be limited by OS

Battery

Dimension	L: 306.9 mm*W: 59.0 mm*T 8.365 mm
Weight	MAX 351.9 g
Type (Chemistry and Cell)	Li-Polymer (4S1P), 4-cell
Voltage	15.6 V
Battery Capacity	90Wh
Charging Time	On Charge Time (0- 100%) * 120 min Off Charge Time (0 – 80%) ** 60 min Off Charge Time (0 – 100%) ** 120 min
Operating Temperature Range	between 10°C (50°F) and 35°C (95°F)
Warranty	1 Year / 3 Year Available
Coin Cell Battery (Model)	CR2016

SECTION IV: BIOS / Certifications / Standards / Environmental

BIOS Specifications

WMI Support	Yes, if it is BIOS Setup change by WMI.
ROM-Based Setup Utility (F1)	Yes

Bootblock Recovery	No
Replicated Setup	Yes, it supported with SRSETUP tool.
Boot Control	Yes, it means Boot order change.
Discrete Mode	No
Memory Change Alert	N/A
Thermal Alert	N/A
Asset Tag	Yes
System/Emergency ROM Flash Recovery with Video	N/A But FW based ROM flash recovery is supported.
Remote Wakeup/Remote Shutdown	Yes, if Remote wakeup is Wake on LAN from S4/S5.
Keyboard-less Operation	N/A
Per-port Control	Yes, if it is I/O port enable/disable by BIOS Setup.
Adaptive Cooling	Yes, if it is thermal & fan control.
Security	Yes, BIOS password / Hard disk password / Finger print
Intel(R) AMT (includes ASF 2.0)	Yes. If you select vPro model
Intel(R) TXT	Yes. If you select vPro model
Memory Modes	N/A
UEFI	UEFI 2.9A (UEFI version is returned as 2.7 but BIOS supports UEFI 2.9A)

EMC & Safety

EMC	Published, Certified Existing Reports EMC – Australia EMC – Belarus EMC – Canada EMC – EU/EFTA EMC – Japan EMC – Kazakhstan EMC – New Zealand EMC – Russia EMC – United Kingdom EMC – USA/Territories
Safety	To access the latest User Guide and Safety and Warranty Guide, go to: https://support.lenovo.com Low Halogen Declaration of Conformance TNOT-2025-0236 Section 9 – Low Halogen Scorecard Homologation PCRB Compliant In the following countries:Afghanistan, Albania, Algeria, Andorra, Angola, Antigua and Barbuda, Argentina, Armenia, Aruba, Australia, Azerbaijan, Bahamas, Bahrain, Bangladesh, Barbados, Belize, Benin, Bermuda, Bolivia, Bosnia and Herzegovina, Botswana, Brazil – No Inmetro 170, Burkina Faso, Burundi, Cambodia, Cameroon, Canada, Cape Verde, Cayman Islands, Central African Republic, Chad, Chile, China, Colombia, Comoros, Congo, Congo Dem. Republic, Costa Rica, Cote D'ivoire – Ivory Coast, Dijbouti, Dominica, Dominican Republic, Ecuador, Egypt, El Salvador,

	Eritrea, Ethiopia, EU/EFTA, Fiji, Gabon, Gambia, Georgia, Ghana, Grenada, Guatemala, Guinea, Guinea-Bissau, Guyana, Haiti, Honduras, Hong Kong, India, Indonesia, Iraq, Israel, Jamaica, Japan, Jordan, Kazakhstan, Kenya, Kuwait, Kyrgyzstan, Laos, Lebanon, Lesotho, Liberia, Libya, Macau, Macedonia, Madagascar, Malawi, Malaysia, Mali, Mauritania, Mauritius, Mayotte, Mexico, Moldova, Mongolia, Montenegro, Morocco, Mozambique, Namibia, Nepal, New Zealand, Nicaragua, Niger, Nigeria, Oman, Pakistan, Panama, Papua New Guinea, Paraguay, Peru, Philippines, Qatar, Rwanda, Saint Kitts and Nevis, Saint Lucia, San Marino, Sao Tome and Principe, Saudi Arabia, Senegal, Serbia, Sierra Leone, Singapore, Solomon Islands, South Africa, South Korea, Sri Lanka, Suriname, Taiwan, Tajikistan, Tanzania, Thailand, Togo, Trinidad and Tobago, Tunisia, Turkiye, Turkmenistan, Uganda, Ukraine, United Arab Emirates, United Kingdom, Uruguay, USA/Territories, Uzbekistan, Vatican City Holy See, Venezuela, Vietnam, Wallis and Futuna, Yemen, Zambia, Zimbabwe

Environmental

Energy Star	ENERGY STAR® Version 9.0 For more information about ENERGY STAR, go to: https://www.energystar.gov
EPEAT	EPEAT Certification Available on select models
IT ECO declaration	The latest environmental information about Lenovo products is available at: https://www.lenovo.com/ecodeclaration
Hazardous Substances	The latest environmental information about Lenovo products is available at: https://www.lenovo.com/ecodeclaration European Union RoHS This Lenovo product, with included parts (cables, cords, and so on) meets the requirements of Directive 2011/65/EU on the restriction of the use of certain hazardous substances in electrical and electronic equipment (“RoHS recast” or “RoHS 2”). For more information about Lenovo worldwide compliance on RoHS, go to: https://www.lenovo.com/rohs-communication

Manageability

Industry Standard Specifications	This product meets the following industry standard specifications for manageability functionality:
Remote Manageability Software Solutions	Lenovo ThinkManagement Console Microsoft System Center Configuration Manager LANDesk Management Suite for Lenovo Vantage Technologies (www.landesk.com/lenovo)
System Software Manager	Lenovo ThinkStation supports software management tools from the ThinkVantage System Update suite: System Update Update Retriever

Service, Support, and Warranty	On-site Warranty and Service: Three-years, limited warranty and service offering delivers on-site, next business-day service for parts and labor and includes free telephone support 8am to 5pm. Global coverage ensures that any product purchased in one country and transferred to another, non-restricted country will remain fully covered under the original warranty and service offering.
Materials Used	90% Recycled Magnesium C Cover 55% Recycled Aluminum D Cover 90% PCC Plastic Speaker Enclosure 90% PCC Plastic Battery Pack Enclosure 30% PCC Plastic 135W & 170W AC Adapter Low Temperature Solder (SSD, fignerprint reader module) Plastic free packaging with 90% recycled and/or FSC certified content (standard)
TCO Certification	TCO 10.0
Disclaimers	1. EPEAT registered where applicable. EPEAT registration varies by country. See www.epeat.net for registration status by country. 2. Product packaging shall contain, on average, a minimum total percentage of 90% by weight of any combination of the following materials: Recycled content, biobased plastic, non-wood biobased fiber material, and/or sustainably forested material